

Title (en)
DIFFUSION BONDED SPUTTERING TARGET ASSEMBLY WITH PRECIPITATION HARDENED BACKING PLATE AND METHOD OF MAKING SAME

Title (de)
DIFFUSIONSGEBUNDENER SPUTTERTARGETAUFBAU MIT TEILCHENGEHÄRTETER TRÄGERPLATTE UND VERFAHREN ZU DESSEN HERSTELLUNG

Title (fr)
ENSEMBLE CIBLE POUR PULVERISATION CATHODIQUE, LIE PAR DIFFUSION, AVEC PLAQUE ARRIERE DURCIE PAR PRECIPITATION, ET PROCEDE DE PRODUCTION DUDIT ENSEMBLE

Publication
EP 0904423 A1 19990331 (EN)

Application
EP 97952525 A 19971204

Priority
• US 9723414 W 19971204
• US 76662996 A 19961213

Abstract (en)
[origin: WO9826107A1] Described is a method for producing a diffusion bonded sputtering target assembly which is thermally treated to precipitation harden the backing plate without compromising the diffusion bond integrity. The method includes heat treating and quenching to alloy solution and artificially age the backing plate material after diffusion bonding to a target. Thermal treatment of the diffusion bonded sputtering target assembly includes quenching by partial-immersion in a quenchant and is performed after diffusion bonding and allows for various tempers in the backing plate.

IPC 1-7
C23C 14/34; B23K 20/00; B23K 31/02; C21D 1/09; C22F 1/08; B32B 15/00; B32B 15/10; B32B 15/20

IPC 8 full level
C22F 1/00 (2006.01); **C21D 1/06** (2006.01); **C21D 1/18** (2006.01); **C22C 21/00** (2006.01); **C22F 1/04** (2006.01); **C22F 1/08** (2006.01); **C22F 1/18** (2006.01); **C23C 14/34** (2006.01)

CPC (source: EP KR)
C22F 1/04 (2013.01 - EP); **C22F 1/08** (2013.01 - EP); **C22F 1/186** (2013.01 - EP); **C23C 14/34** (2013.01 - KR); **C23C 14/3407** (2013.01 - EP)

Designated contracting state (EPC)
AT BE CH DE DK ES FI FR GB IE IT LI LU NL PT SE

DOCDB simple family (publication)
WO 9826107 A1 19980618; CN 1211287 A 19990317; EP 0904423 A1 19990331; EP 0904423 A4 19990908; JP 3485577 B2 20040113; JP H11504391 A 19990420; KR 100315076 B1 20020228; KR 19990082538 A 19991125; TW 490499 B 20020611; TW I232887 B 20050521

DOCDB simple family (application)
US 9723414 W 19971204; CN 97192237 A 19971204; EP 97952525 A 19971204; JP 52706598 A 19971204; KR 19980706274 A 19980813; TW 86118776 A 19971212; TW 91105167 A 19971212